

Anti-Surge Thick Film Chip Resistors

Type: **ERJ PA2, P03, PA3, P06, P08, P14**



Features

- ESD surge characteristics superior to standard metal film resistors
- High reliability
Metal glaze thick film resistive element and three layers of electrodes
- Suitable for both reflow and flow soldering
- High power ... 0.20 W : 0402 inch / 1005 mm size (ERJPA2), 0603 inch / 1608 mm size (ERJP03)
0.25 W : 0603 inch / 1608 mm size (ERJPA3)
0.50 W : 0805 inch / 2012 mm size (ERJP06), 1210 inch / 3225 mm size (ERJP14)
0.66 W : 1206 inch / 3216 mm size (ERJP08)
- Reference Standards... IEC 60115-8, JIS C 5201-8, EIAJ RC-2134B
- AEC-Q200 qualified
- RoHS compliant

■ **As for Packaging Methods, Land Pattern, Soldering Conditions and Safety Precautions,**
Please see Data Files

Explanation of Part Numbers

	1	2	3	4	5	6	7	8	9	10	11	12
	E	R	J	P	0	6	D	1	0	0	2	V

Product Code	Size, Power Rating	
Thick Film Chip Resistors	Code	Inch Power R.
	PA2	0402 0.20 W
	P03	0603 0.20 W
	PA3	0603 0.25 W
	P06	0805 0.50 W
	P08	1206 0.66 W
	P14	1210 0.50 W

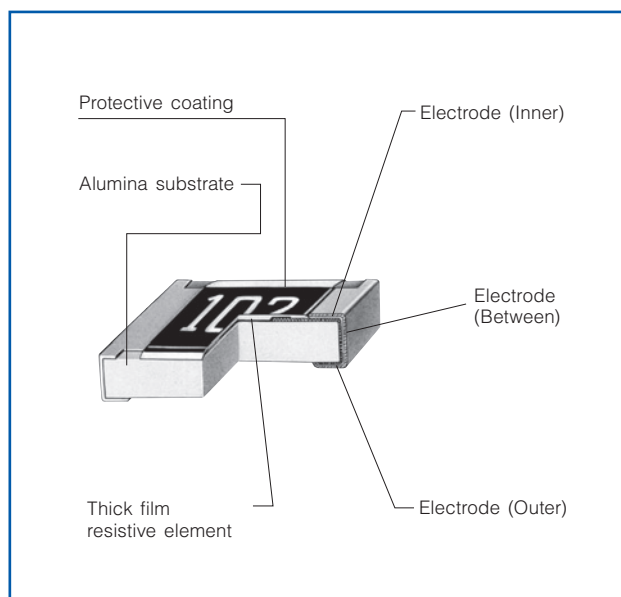
Resistance Tolerance	
Code	Tolerance
D	± 0.5 %
F	± 1 %
J	± 5 %

Resistance Value

The first two or three digits are significant figures of resistance and the third or 4th one denotes number of zeros following.
Three digit type (±5 %),
four digit type (±1 %, ±0.5 %)
Example: 222→2.2k Ω, 1002→10k Ω

Packaging Methods		
Code	Packaging	Part No.
X	Punched Carrier Taping 2 mm pitch, 10,000 pcs.	ERJPA2
V	Punched Carrier Taping 4 mm pitch, 5,000 pcs.	ERJP03 ERJPA3 ERJP06 ERJP08
U	Embossed Carrier Taping 4 mm pitch, 5,000 pcs.	ERJP14

Construction



Dimensions in mm (not to scale)



Part No.	Dimensions (mm)					Mass (Weight) [g/1000 pcs.]
	L	W	a	b	t	
ERJPA2	1.00 ^{+0.05}	0.50 ^{+0.05}	0.20 ^{+0.15}	0.25 ^{+0.05}	0.35 ^{+0.05}	0.8
ERJP03	1.60 ^{+0.15}	0.80 ^{+0.15} _{-0.05}	0.15 ^{+0.15} _{-0.10}	0.30 ^{+0.15}	0.45 ^{+0.10}	2
ERJPA3	1.60 ^{+0.15}	0.80 ^{+0.15} _{-0.05}	0.15 ^{+0.15} _{-0.10}	0.25 ^{+0.10}	0.45 ^{+0.10}	2
ERJP06	2.00 ^{+0.20}	1.25 ^{+0.10}	0.25 ^{+0.20}	0.40 ^{+0.20}	0.60 ^{+0.10}	4
ERJP08	3.20 ^{+0.05} _{-0.20}	1.60 ^{+0.05} _{-0.15}	0.40 ^{+0.20}	0.50 ^{+0.20}	0.60 ^{+0.10}	10
ERJP14	3.20 ^{+0.20}	2.50 ^{+0.20}	0.35 ^{+0.20}	0.50 ^{+0.20}	0.60 ^{+0.10}	16

Ratings

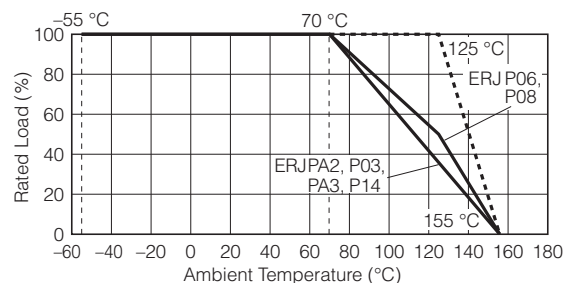
Part No. (inch size)	Power Rating ⁽³⁾ at 70 °C (W)	Limiting Element Voltage ⁽¹⁾ (V)	Maximum Overload Voltage ⁽²⁾ (V)	Resistance Tolerance (%)	Resistance Range (Ω)	T.C.R. ($\times 10^{-6}/^{\circ}\text{C}$)	Category Temperature Range (°C)	AEC-Q200 Grade
ERJPA2 (0402)	0.20	50	100	$\pm 0.5, \pm 1$	10 to 1M (E24, E96)	± 100	-55 to +155	Grade 0
				± 5	10 to 1M (E24)	± 200		
ERJP03 (0603)	0.20	150	200	± 0.5	10 to 1M (E24, E96)	± 150	-55 to +155	Grade 0
				± 1	10 to 1M (E24, E96)	± 200		
				± 5	1 to 1M (E24)	$\begin{matrix} R < 10 \Omega & : -150 \text{ to } +400 \\ 10 \Omega \leq R & : \pm 200 \end{matrix}$		
ERJPA3 (0603)	0.25	150	200	$\pm 0.5, \pm 1$	10 to 1M (E24, E96)	± 100	-55 to +155	Grade 0
				± 5	1 to 1.5M (E24)	± 200		
ERJP06 (0805)	0.50	400	600	$\pm 0.5, \pm 1$	10 to 1M (E24, E96)	$\begin{matrix} R < 33 \Omega & : \pm 300 \\ 33 \Omega \leq R & : \pm 100 \end{matrix}$	-55 to +155	Grade 0
				± 5	1 to 3.3M (E24)	$\begin{matrix} R < 10 \Omega & : -100 \text{ to } +600 \\ 10 \Omega \leq R & : \pm 300 \\ 33 \Omega \leq R & : \pm 200 \end{matrix}$		
ERJP08 (1206)	0.66	500	1000	$\pm 0.5, \pm 1$	10 to 1M (E24, E96)	± 100	-55 to +155	Grade 0
				± 5	1 to 10M (E24)	$\begin{matrix} R < 10 \Omega & : -100 \text{ to } +600 \\ 10 \Omega \leq R & : \pm 200 \end{matrix}$		
ERJP14 (1210)	0.50	200	400	$\pm 0.5, \pm 1$	10 to 1M (E24, E96)	± 100	-55 to +155	Grade 0
				± 5	1 to 1M (E24)	$\begin{matrix} R < 10 \Omega & : -100 \text{ to } +600 \\ 10 \Omega \leq R & : \pm 200 \end{matrix}$		

- (1) Rated Continuous Working Voltage (RCWV) shall be determined from $\text{RCWV} = \sqrt{\text{Power Rating} \times \text{Resistance Values}}$, or Limiting Element Voltage listed above, whichever less.
 (2) Overload Test Voltage (OTV) shall be determined from $\text{OTV} = \text{Specified Magnification (refer to performance)} \times \text{RCWV}$ or Maximum Overload Voltage listed above, whichever less.
 (3) Use it on the condition that the case temperature is below the upper category temperature.

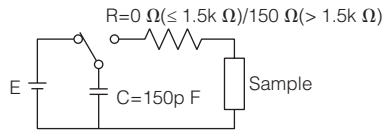
Power Derating Curve

For resistors operated in ambient temperatures above 70 °C, power rating shall be derated in accordance with the figure on the right.

* When the temperature of ERJP14 is 155 °C or less, the derating start temperature can be changed to 125 °C. (See the dotted line)

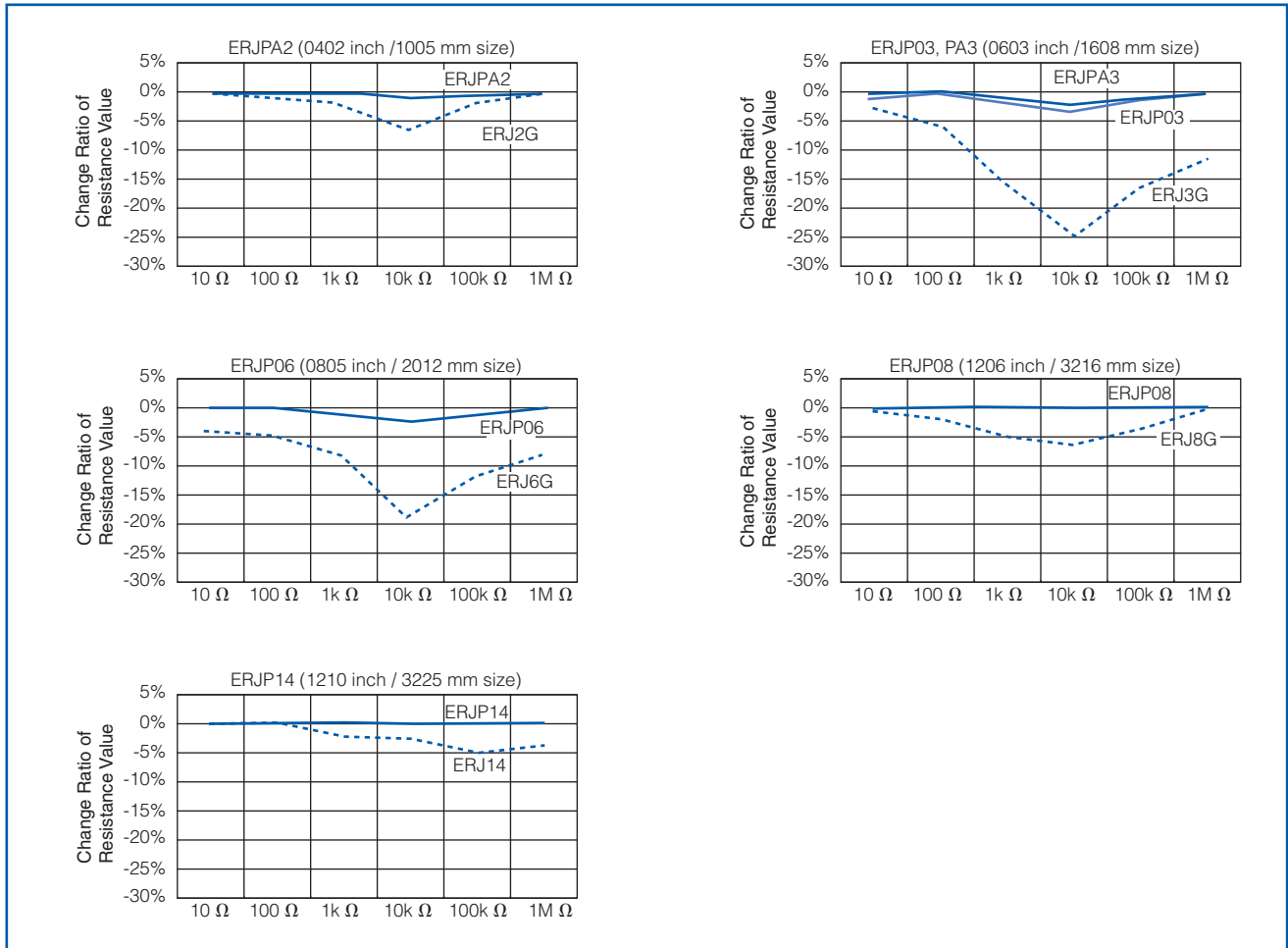


ESD Characteristic



0402 inch size : E=±1k V
 0603, 0805, 1206, 1210 inch size : E=±3k V

— Anti-Surge Thick Film Chip Resistors(ERJP Type)
 - - - Thick Film Chip Resistors(ERJ Type)



Performance

Test Item	Performance Requirements	Test Conditions
Resistance	Within Specified Tolerance	20 °C
T. C. R.	Within Specified T. C. R.	+25 °C/+155 °C (ERJPA2 : +125 °C)
Overload	±2% Only when it is ERJP03 (D), P14 (D) : ±0.5%	ERJP06 : Rated Voltage×1.77, 5 s ERJPA2, ERJPA3, ERJP08 : Rated Voltage×2.0, 5 s ERJP03, ERJP14 : Rated Voltage×2.5, 5 s
Resistance to Soldering Heat	D : ±0.5%, F, J : ±1%	270 °C, 10 s
Rapid Change of Temperature	±1%	-55 °C (30 min.) / +155 °C (30 min.) , 100 cycles
High Temperature Exposure	±1%	+155 °C, 1000 h
Damp Heat, Steady State	±1%	60 °C, 90% to 95%RH, 1000 h
Load Life in Humidity	±3% Only when it is ERJP03 (D), P14 (D) : ±1%	60 °C, 90% to 95%RH, Rated Voltage, 1.5 h ON / 0.5 h OFF cycle, 1000 h
Endurance at 70 °C	±3% Only when it is ERJP03 (D), P14 (D) : ±1%	70 °C, Rated Voltage, 1.5 h ON / 0.5 h OFF cycle, 1000 h

Design and specifications are each subject to change without notice. Ask factory for the current technical specifications before purchase and/or use.
 Should a safety concern arise regarding this product, please be sure to contact us immediately.

⚠ Safety Precautions (Common precautions for Surface Mount Resistors)

The following are precautions for individual products. Please also refer to the common precautions for Fixed Resistors in this catalog.

1. Take measures against mechanical stress during and after mounting of Surface Mount Resistors (hereafter called the resistors) so as not to damage their electrodes and protective coatings.
Be careful not to misplace the resistors on the land patterns. Otherwise, solder bridging may occur.
2. Keep the rated power and ambient temperature within the specified derating curve.
Some circuit boards, wiring patterns, temperatures of heat generated by adjacent components, or ambient temperatures can become factors in the rise of the temperature of the resistors, regardless of the level of power applied. Therefore, check the conditions before use and optimize them so as not to damage the boards and peripheral components.
Make sure to contact us before using the resistors under special conditions.
3. If a transient load (heavy load in a short time) like a pulse is expected to be applied, check and evaluate the operations of the resistors when installed in your products before use.
Never exceed the rated power. Otherwise, the performance and/or reliability of the resistors may be impaired.
4. Before using halogen-based or other high-activity flux, check the possible effects of the flux residues on the performance and reliability of the resistors.
5. When soldering with a soldering iron, never touch the resistors' bodies with the tip of the soldering iron. When using a soldering iron with a high temperature tip, finish soldering as quickly as possible (within three seconds at 350 °C max.).
6. As the amount of applied solder becomes larger, the mechanical stress applied to the resistors increases, causing problems such as cracks and faulty characteristics. Avoid applying an excessive amounts of solder.
7. When the resistors' protective coatings are chipped, flawed, or removed, the characteristics of the resistors may be impaired. Take special care not to apply mechanical shock during automatic mounting or cause damage during handling of the boards with the resistors mounted.
8. Do not apply shock to the resistors or pinch them with a hard tool (e.g. pliers and tweezers). Otherwise, the resistors' protective coatings and bodies may be chipped, affecting their performance.
9. Avoid excessive bending of printed circuit boards in order to protect the resistors from abnormal stress.
10. Do not immerse the resistors in solvent for a long time. Before using solvent, carefully check the effects of immersion.
11. Transient voltage
If there is a possibility that the transient phenomenon (significantly high voltage applied in a short time) may occur or that a high voltage pulse may be applied, make sure to evaluate and check the characteristics of Fixed Metal (Oxide) Film Resistors mounted on your product rather than only depending on the calculated power limit or steady-state conditions to complete the design or decide to use the resistors.
12. Do not apply excessive tension to the terminals.

⚠ Safety Precautions (Common precautions for Fixed Resistors)

- When using our products, no matter what sort of equipment they might be used for, be sure to make a written agreement on the specifications with us in advance. The design and specifications in this catalog are subject to change without prior notice.
- Do not use the products beyond the specifications described in this catalog.
- This catalog explains the quality and performance of the products as individual components. Before use, check and evaluate their operations when installed in your products.
- Install the following systems for a failsafe design to ensure safety if these products are to be used in equipment where a defect in these products may cause the loss of human life or other significant damage, such as damage to vehicles (automobile, train, vessel), traffic lights, medical equipment, aerospace equipment, electric heating appliances, combustion/gas equipment, rotating equipment, and disaster/crime prevention equipment.
- * Systems equipped with a protection circuit and a protection device
- * Systems equipped with a redundant circuit or other system to prevent an unsafe status in the event of a single fault

(1) Precautions for use

- These products are designed and manufactured for general and standard use in general electronic equipment (e.g. AV equipment, home electric appliances, office equipment, information and communication equipment)
- These products are not intended for use in the following special conditions. Before using the products, carefully check the effects on their quality and performance, and determine whether or not they can be used.
 1. In liquid, such as water, oil, chemicals, or organic solvent
 2. In direct sunlight, outdoors, or in dust
 3. In salty air or air with a high concentration of corrosive gas, such as Cl₂, H₂S, NH₃, SO₂, or NO₂
 4. Electric Static Discharge (ESD) Environment
These components are sensitive to static electricity and can be damaged under static shock (ESD). Please take measures to avoid any of these environments.
Smaller components are more sensitive to ESD environment.
 5. Electromagnetic Environment
Avoid any environment where strong electromagnetic waves exist.
 6. In an environment where these products cause dew condensation
 7. Sealing or coating of these products or a printed circuit board on which these products are mounted, with resin or other materials
- These products generate Joule heat when energized. Carefully position these products so that their heat will not affect the other components.
- Carefully position these products so that their temperatures will not exceed the category temperature range due to the effects of neighboring heat-generating components. Do not mount or place heat-generating components or inflammables, such as vinyl-coated wires, near these products.
- Note that non-cleaning solder, halogen-based highly active flux, or water-soluble flux may deteriorate the performance or reliability of the products.
- Carefully select a flux cleaning agent for use after soldering. An unsuitable agent may deteriorate the performance or reliability. In particular, when using water or a water-soluble cleaning agent, be careful not to leave water residues. Otherwise, the insulation performance may be deteriorated.

(2) Precautions for storage

The performance of these products, including the solderability, is guaranteed for a year from the date of arrival at your company, provided that they remain packed as they were when delivered and stored at a temperature of 5 °C to 35 °C and a relative humidity of 45 % to 85 %.

Even within the above guarantee periods, do not store these products in the following conditions. Otherwise, their electrical performance and/or solderability may be deteriorated, and the packaging materials (e.g. taping materials) may be deformed or deteriorated, resulting in mounting failures.

1. In salty air or in air with a high concentration of corrosive gas, such as Cl₂, H₂S, NH₃, SO₂, or NO₂
2. In direct sunlight

<Package markings>

Package markings include the product number, quantity, and country of origin. In principle, the country of origin should be indicated in English.

单击下面可查看定价，库存，交付和生命周期等信息

[>>Panasonic\(松下\)](#)